

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Yasunori INOUE et al.

Serial No.: 08/921,250

Group Art Unit: 1765

Filed: August 29, 1997

Examiner: George GOUDREAU

For: FABRICATION METHOD OF SEMICONDUCTOR DEVICE AND  
ABRASIVE LIQUID USED THEREIN

**RESPONSE TO THE RESTRICTION REQUIREMENT  
DATED OCTOBER 27, 1999**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Date: November 9, 1999

Sir:

This paper is submitted in response to the Official Action dated October 27, 1999.

In the Action, restriction is required between Group (I), claims 1 - 28 drawn to a method for cmp polishing semiconductor substrate; and Group (II), claims 29 - 30 drawn to a cmp polishing composition.

Applicants hereby elect the subject matter of Group (I), claims 1 - 28 for prosecution in this application. This election is made without traverse, it being understood that the applicants' rights to the filing of a Divisional application directed to the non-elected subject matter under 35 USC §120 and 35 USC §121 are retained.



RECEIVED  
NOV 10 1999  
TC 1700 MAIL ROOM

In the event that this paper is not timely filed, applicants hereby petition for an appropriate extension of time. The fee for any such extension may be charged to our Deposit Account No. 01-2340.

In the event any additional fees are required in connection with this response, please charge our Deposit Account No. 01-2340.

Respectfully submitted,

ARMSTRONG, WESTERMAN, HATTORI,  
McLELAND & NAUGHTON



Mel R. Quintos  
Attorney for Applicants  
Reg. No. 31,898

Atty. Docket No. 970813

1725 K Street, N.W., Suite 1000  
Washington, DC 20006

Tel: (202) 659-2930  
Fax: (202) 887-0357

MRQ/lrj

RECEIVED  
MAY 10 1999  
TC 1700 MAIL ROOM